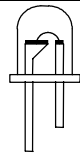




VDD CONTROL
RGB LED IC

电源控制
三色灯 LED IC

LED FLASH	
M1346	

FEATURES 功能叙述

- Minimum external component (without limit current resister).
- Built-in oscillator.
- Power on continual function.

P/N	FUNCTION
M1346-1	七彩渐明渐暗
M1346-2	七彩跳闪
M1346-3	七彩跳闪 + 七彩渐明渐暗

APPLICATION 产品应用

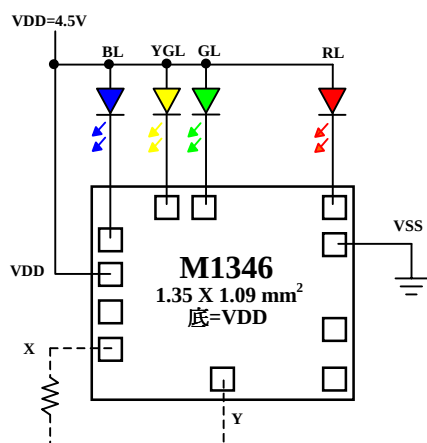
- Blinking LED, Function indicator, R.G.B Mix etc..

ELECTRICAL CHARACTERISTICS 电气规格

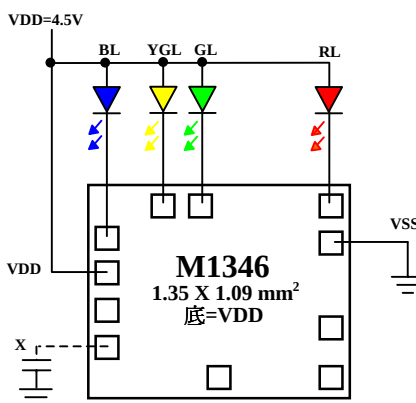
(@V_{DD}=4.5V unless otherwise specified)

Characteristics	Sym.	Min.	Typ.	Max.	Unit	REMARKS
工作电压 Operating Voltage	V _{DD}	—	4.5	5	V	
工作电流 Operating Current	I _{OP}	—	0.1	0.5	mA	No load
静态电流 Quiescent Current	I _{SB}	—	1	—	μ A	One-shot mode
推动电流 Driving Current	I _{OL}	20	—	—	mA	@V _{DS} = 1.2 V
振荡频率 Oscillator Frequency	F _{OSC}	—	110	—	KHz	±30% TOL.
工作温度 Operating Temperature	Temp.	0	25	60	°C	

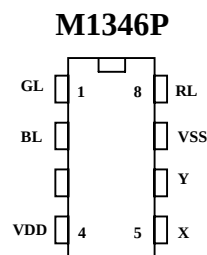
APPLICATION DIAGRAM 参考电路图



* 外加电阻加快



* 外加电容减慢



LED Chip			Vf (V)		Iv (mcd)	
Emitted color	Material	λ p(nm)	Typ.	Max.	At Ir (mA)	Typ.
Red	Algainp	635	1.9	2.1	20	120
Green	Ingan	525	3.1	3.5		100
Blue	Ingan	470	3.65	4.0		80
Yellow Green	Algainp	550	2.0	2.3		120

*All specs and applications shown above subject to change without prior notice.

(以上电路及规格仅供参考,本公司得径行修正)



~ 華半導體股份有限公司
MOSDESIGN SEMICONDUCTOR CORP.

TAIPEI : TEL : 886-2- 22783733

FAX : 886-2- 22783633

H.K. : TEL : 852- 27569109

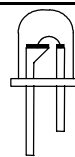
FAX : 852- 27566961

VDD CONTROL
RGB LED IC

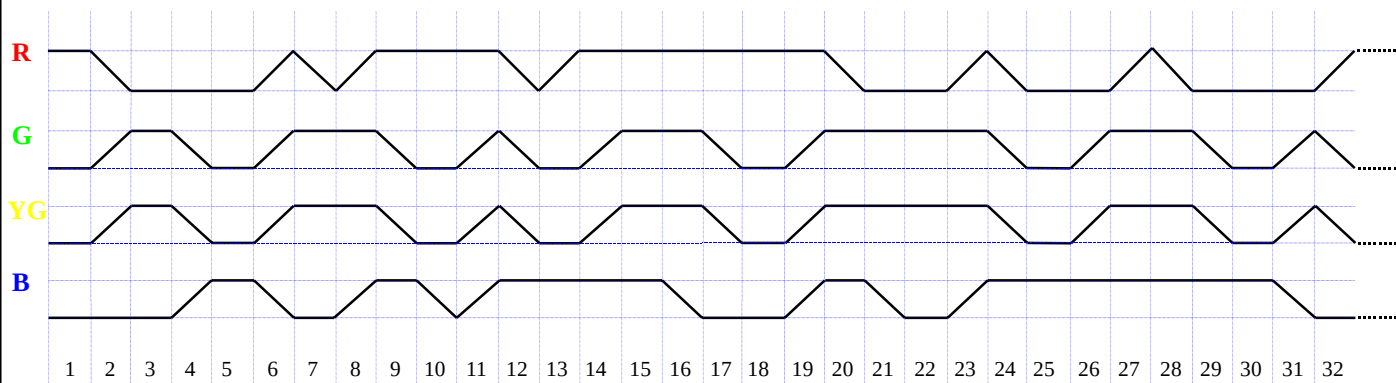
电源控制
三色灯 LED IC

LED FLASH

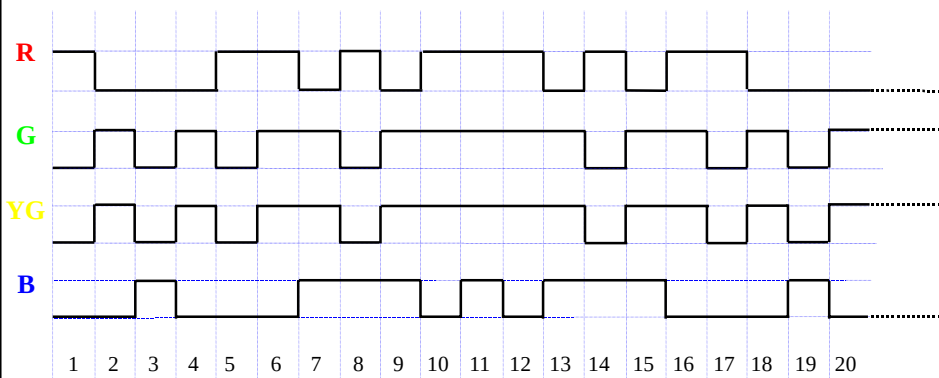
M1346



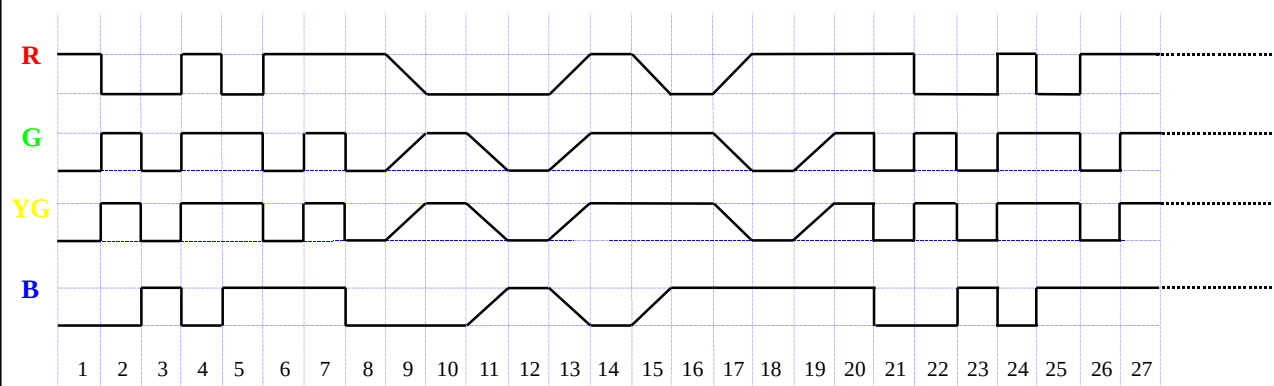
* M1346-1 (七彩渐明渐暗)



* M1346-2 (七彩跳闪)



* M1346-3 (七彩跳闪 + 七彩渐明渐暗)





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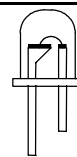
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VDD CONTROL
RGB LED IC

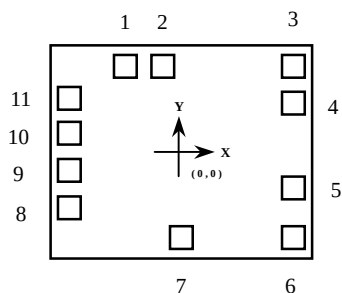
电源控制
三色灯 LED IC

LED FLASH

M1346



PAD ASSIGNMENT & POSITION



UNIT : um			
No.	NAME	X	Y
1	YG	-282.80	423.20
2	GL	-92.40	423.20
3	RL	552.40	423.20
4	VSS	552.40	243.20
5	TEST2	552.40	-184.20
6	TEST1	559.10	-423.20
7	Y	2.20	-423.20
8	X	-552.50	-264.70
9	OPT	-552.50	-77.70
10	VDD	-552.50	109.30
11	BL	-552.50	274.30

* CHIP SIZE ~ 1.35 x 1.09 mm²

* IC substrate should be connected to VDD in PCB (PCB 上 IC 必须接 VDD)